



1A, 200V - 600V Surface Mount Super Fast Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Low power loss, high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21



Case: SMAF

Molding compound: UL flammability classification rating 94V-0

Moisture sensitivity level: level 1, per J-STD-020

Packing code with suffix "G" means green compound (halogen-free)

Terminal: Matte tin plated leads, solderable per J-STD-002

Meet JESD 201 class 1A whisker test Polarity: Indicated by cathode band Weight: 35 mg (approximately)







MAXIMUM RATINGS AND ELECTRICAL CHAR	ACTERISTIC	S (T _A =25°C unle	ess otherwise note	d)	
PARAMETER	SYMBOL	ES1DF	ES1GF	ES1JF	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	V
Maximum RMS voltage	V_{RMS}	140	280	420	V
Maximum DC blocking voltage	V _{DC}	200	400	600	V
Maximum average forward rectified current	I _{F(AV)}	1		А	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30			А
Maximum instantaneous forward voltage (Note 1) @ 1 A	V _F	1.00	1.30	1.70	V
Maximum reverse current @ rated V _R T _J =25°C T _J =125°C		5 100			
T _J =125°C	I _R				μΑ
Typical junction capacitance (Note 2)	CJ	9		pF	
Maximum reverse recovery time (Note 3)	t _{rr}	35		ns	
Typical thermal resistance	$R_{\theta JL}$	35		°C/W	
Typical thermal resistance	$R_{\theta JA}$	85			C/VV
Operating junction temperature range	T _J	- 55 to +150			°C
Storage temperature range	T _{STG}	- 55 to +150 °C			°C

Note 1: Pulse test with PW=300µs, 1% duty cycle Note 2: Measured at 1 MHz and applied V_R=4.0 V Note 3: Test conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$

Version: B1604



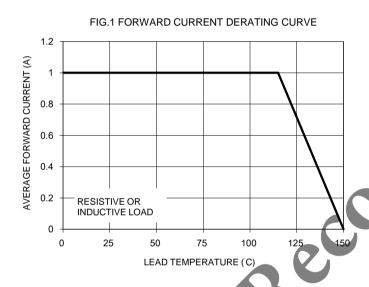
ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
ES1xF	R3	G	SMAF	3,000 / 7" Plastic reel	
(Note 1, 2)	R2	9	SMAF	10,000 / 13" Paper reel	

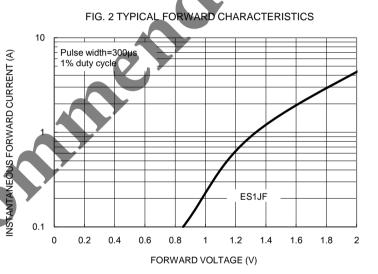
Note 1: "x" defines voltage from 200V (ES1DF) to 600V (ES1JF)

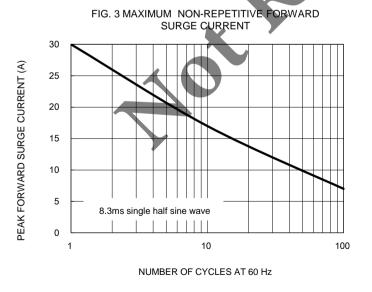
Note 2: Whole series with green compound

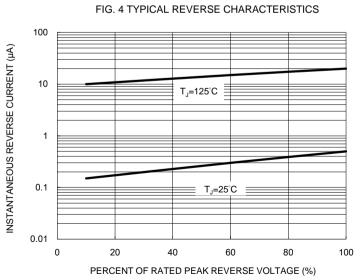
EXAMPLE						
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
ES1DF R3G	ES1DF	R3	G	Green compound		

RATINGS AND CHARACTERISTICS CURVES (T_A=25°C unless otherwise noted)









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Taiwan Semiconductor

FIG. 5 TYPICAL JUNCTION CAPACITANCE

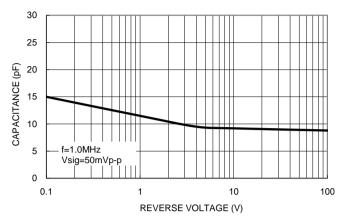
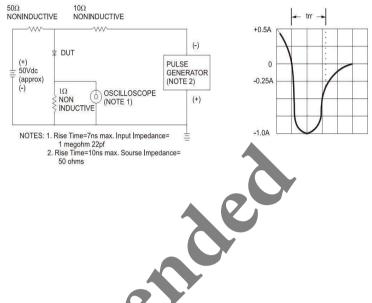
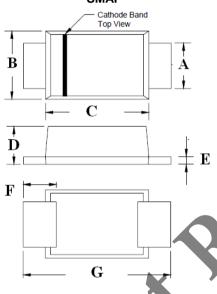


FIG.6 REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



PACKAGE OUTLINE DIMENSIONS

SMAF



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.25	1.60	0.049	0.063	
В	2.40	2.80	0.094	0.110	
C	3.30	4.30	0.130	0.169	
D	0.90	1.10	0.035	0.043	
E	0.10	0.25	0.004	0.010	
F	0.70	1.20	0.028	0.047	
G	4.40	5.20	0.173	0.205	

MARKING DIAGRAM



P/N = Specific Device Code G = Green compound Code

YW = Date Code F = Factory Code





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